

查询CPD15供应商
PROCESS CPD15
Ultra Fast Rectifier
500mA Glass Passivated Rectifier Chip

捷多邦，专业PCB打样工厂，24小时加急出货™

Central
Semiconductor Corp.

PROCESS DETAILS

Process	GLASS PASSIVATED MESA
Die Size	25 x 25 MILS
Die Thickness	9.5 MILS
Anode Bonding Pad Area	14.5 x 14.5 MILS
Top Side Metalization	Au - 5,000Å
Back Side Metalization	Au - 2,000Å

GEOMETRY



BACKSIDE CATHODE

R0

GROSS DIE PER 4 INCH WAFER

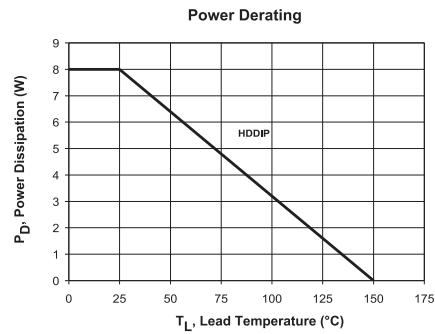
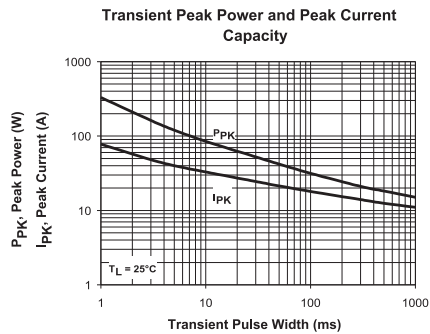
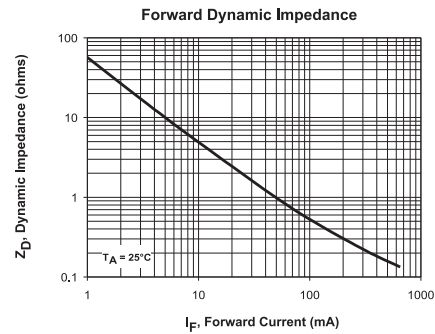
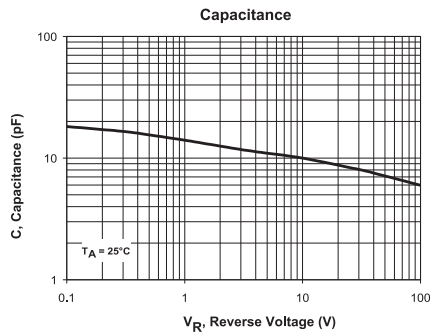
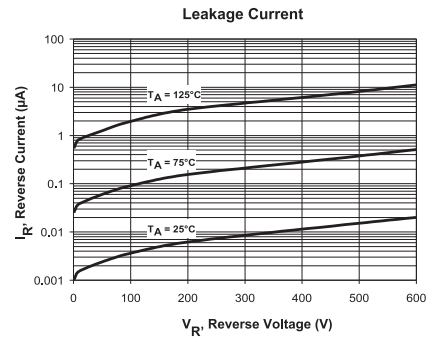
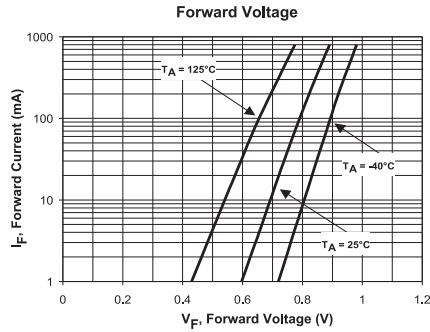
18,080

PRINCIPAL DEVICE TYPES

CBRH DU-02 Series

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R2 (19-September 2003)



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